

PRESS RELEASE

For Immediate Release

Rugged Gigahertz Probe for RF and Power Integrity Testing

Strong RF probe for direct probing on circuit components or uneven surfaces

Santa Clara, California, January 28, 2014 – PacketMicro announces the new additions of RF probe and calibration substrate to its HSProbe™ product family for printed-circuit board testing. Designed by engineers for engineers, the 12-GHz probe comprises rugged BeCu probe tips, making it perfect for RF and power-integrity testing that requires direct probing on top of circuit components or test pads on an uneven surface.

“Constant shrinking size of circuit components makes soldering semi-rigid RF cables to test gigahertz circuits impractical,” said Richard Zai, PacketMicro CTO. “The rugged RF probe and calibration substrate allow engineers to perform probe-tip calibration for accurate and repetitive RF measurements.”

HSProbe™ family is specifically designed for bench-top testing of large PCBs. The RF probe comes in five different probe pitches, and the calibration substrate (TCS50) provides the SOLT standards for probe-tip calibration. Together, the RF probes (RP-GR-1215 series), PCB holder (VPH100 series) and Easy Positioner (TP60) are ideal for S-Parameter and TDR measurements required in RF, power-integrity, and signal-integrity measurements. Please stop by Booth#742 at DesignCon 2014 held at Santa Clara Convention Center, Santa Clara, California on January 29 – 30, 2014, for product demonstration.

Product Information

For RF Probes:

RP-GR-121505, 12 GHz, 1.5", 0.5 mm pitch

RP-GR-121508, 12 GHz, 1.5", 0.8 mm pitch

RP-GR-121510, 12 GHz, 1.5", 1.0 mm pitch

PacketMicro also supports customized probe pitches from 0.2 mm to 1.2 mm.

For Calibration substrate:

TCS50

All products are available now for purchase at www.packetmicro.com.

About PacketMicro

PacketMicro, located in Silicon Valley, provides a wide range of gigahertz probing solutions and offers world-class signal integrity design services. In addition, PacketMicro offers one-stop engineering services in the areas of wireless sensor networks, radio frequency identification (RFID), and high-speed FPGA. For more information, please visit www.packetmicro.com.

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